



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Kazutaka SHIBATA

Application No.: 10/088,163

Filed: March 15, 2002

For: SEMICONDUCTOR DEVICE WITH CHIP-ON-CHIP CONSTRUCTION
JOINED VIA A LOW-MELTING POINT METAL LAYER (As Amended)

Attorney Docket No.: KWM-0001

Examiner: P. Greene

Art Unit: 2826

Confirmation No. 1108

AMENDMENT UNDER 37 C.F.R. §1.111

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

I. INTRODUCTORY COMMENTS

In response to the Office Action dated June 5, 2003, the period for response being extended to November 5, 2003, by the Petition for Extension of Time filed herewith, please amend the above-identified application as set forth below.

Claims 1-4, 7-20 and 25 are pending in the application. By this Amendment, claims 1-3, 7-11, 16, 17 and 20 are amended and claims 5 and 6 are canceled.

Applicant expresses his appreciation for the Examiner's indication of allowable subject matter in claims 5, 6, 9, 18, 19 and 25.

II. AMENDMENTS TO THE DRAWINGS

(There are no amendments to the drawings)

III. AMENDMENTS TO THE SPECIFICATION

(There are no amendments to the specification)

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